

REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.16	阿树

2-1.00 [0.039] 4.25 [0.167] 2.11 [0.083]



11.52 [0.454]



8.06 [0.317]

7.34 [0.289]

(0.07 [0.003])

CONNECTOR CENTER CARD CENTER

0.76 [0.030]

5.66 [0.223]

9.82 [0.386]

11.16 [0.439] CARD SLOT

COMPOSITION OF DETECTION

CARD DETECT(SW)

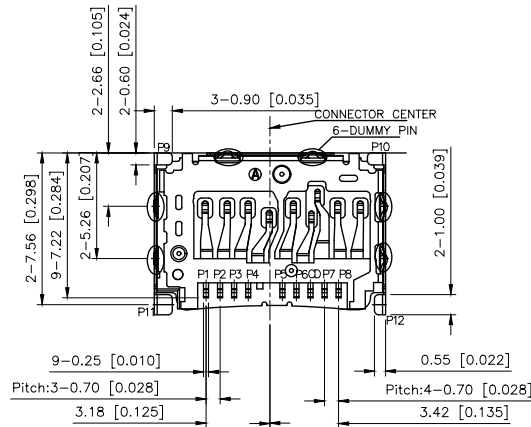
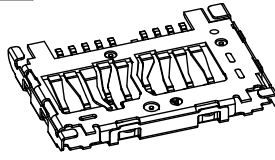
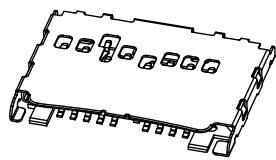
P6-CD

CARD DETECTION/SWITCH

CARD INSTALLATION:ON

NON CARD:OFF

WHEN BECOMIOG SW ON CARD INSTALLATION



NOTE:

1. 材料 Material:

- 1-1 外壳 Housing:High Temperature Thermoplastic, (LCP MG350)Color Black U 94V-0
- 1-2 端子 Contact:Phosphor Bronze(C5210R-SH T=0.12mm)
- 1-3 外壳 Shell:SUS304-HT=0.10mm

2. 电镀 Plating:

- 2-1 Contact terminal:
Contact area: Gold 2u" Min.Middle Pd-Ni au" min.
Solder area: Gold 1u" Min.
Underplating: Ni overall 80U" Min.
- 2-2 外壳 Shell:
底镀 Underplating: Ni overall 30U" Min.
焊接区 Solder area: Gold 1u" Min .

3. 规格 Specification:

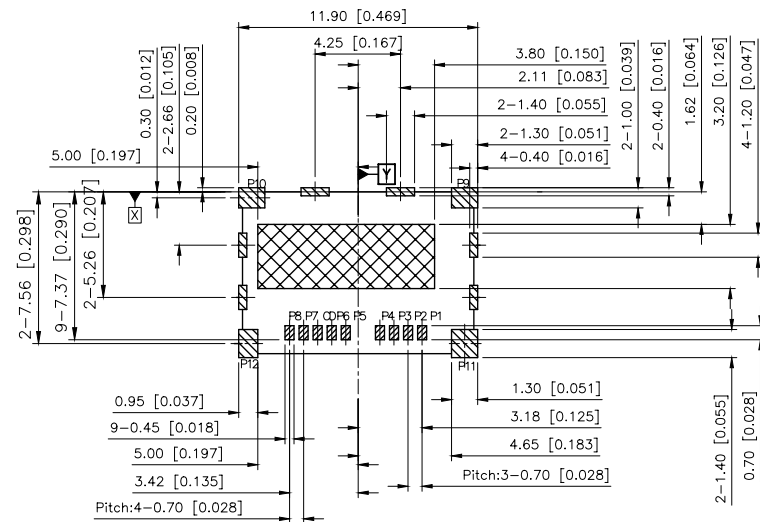
- 3-1.接触电流 Contact Current Rating:0.5Amperes.
- 3-2.介电耐受电压 Dielectric Withstanding Voltage:AC500V r.m.s.
- 3-3.绝缘电阻 Insulation Resistance:1000 Megohms Minimum At DC 500V.
- 3-4.接触电阻 Contact Resistance:100 mΩ Maximum.
- 3-5.寿命 Mating Cyeles:5,000 Cycles.
- 3-6.工作温度 Operating Temperature:-25℃~+60℃.

4. Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC

- 5.Recommending A Metal More Than 0.15mm Thick.
- Please Confirm Solderadility,If Use A Metal Mask Less Than 0.15mm Thick.

Recommended PCB Layout Top View (Tolerance±0.05)

- PAD AREA
- KEEP OUT AREA
- NO COPPER AREA
- GND PATTERN ONLY



Pin	Define
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
CD	CARD DETECT
P7	DAT0
P8	DAT1
P9-P12	GND

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE:
CHECKED		UNIT: mm/in	TF CARD CONN
APPROVED		SIZE: A4	PART NO.:
			XKTF-7131-1
			DWG NO.:
			X-XKTF-7131-1

SCALE	PAGE	REVISION
N/A	1/1	A1